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Part 1: Mechanical reliability under shock

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Introduction

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



47/2905/CD

COMMITTEE DRAFT (CD)

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IEC TC 47 : SEMICONDUCTOR DEVICES	
SECRETARIAT: Korea, Republic of	SECRETARY: Mr Cheolung Cha
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	

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TITLE:

Semiconductor devices - Reliability evaluation methods for vibration energy harvesters - Part 1 : Mechanical reliability under shock

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES

–RELIABILITY EVALUATION METHODS FOR VIBRATION ENERGY HARVESTERS–

Part 1: Mechanical Reliability Under Shock

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The text of this International Standard is based on the following documents:

Draft	Report on voting
XX/XX/FDIS	XX/XX/RVD